

VERSION WITH MARKINGS SHOWING THE CHANGES MADE

IN THE CLAIMS:

Claims 1, 9, 19, 35, 42, 47, 52, and 57 have been amended as follows:

1. (Five Times Amended) A system for electrically coupling a semiconductive device to an electrical apparatus, the system comprising:

an interposer, the interposer comprising:

a substrate comprised of an electrically insulating ceramic material, the substrate having an outermost surface and being configured for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said substrate; and

a plurality of electrical conductors on the substrate, each electrical conductor having a receiving end for connecting to the semiconductive device at electrically conductive terminals of said semiconductive device, and a terminal end for connecting to an electrical apparatus, such that electrical circuitry within the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to said plurality of receiving ends of the electrical conductors and said plurality of terminal ends of the electrical conductors are connected to the electrical apparatus; and

a connector for holding the semiconductive device stationary relative to the interposer by contact engagement with said semiconductive device and with said substrate, wherein said contact engagement is effectuated through direct contact between the connector with the semiconductor device [directly] or through an adhesive in contact with said connector, and wherein at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said substrate.

9. (Five Times Amended) A system for testing a semiconductive device, the system comprising:

an electrical testing apparatus;

a semiconductive device having an electrical circuitry therein electrically connected to an electrical lead projecting therefrom;

an interposer, the interposer comprising:

a substrate comprised of an electrically insulating material selected from the group consisting of glass, alumina, glass ceramic, nonmetallic nitride, aluminum nitride, nonmetallic carbide, and mixtures and derivatives thereof, the substrate having an outermost surface and being configured for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface, and is unimbedded into said substrate; and

an electrical conductor on the substrate, the electrical conductor having a receiving end for connecting to the electrical lead of the

semiconductive device and a terminal end for connecting to the electrical testing apparatus, whereby the semiconductive device is electrically coupled to the electrical testing apparatus when the electrical lead of the semiconductive device is in contact with the receiving end of the electrical conductor and the terminal end of the electrical conductor is in electrical communication with the electrical testing apparatus, wherein said receiving end and said terminal lead are connected and free of contact engagement with any other element other than said substrate and said semiconductive device; and

a connector for holding the semiconductive device stationary relative to the interposer by contact engagement with said semiconductive device and with said substrate, wherein said contact engagement is effectuated through direct contact between the connector with the semiconductor device [directly] or through an adhesive in contact with said connector.

19. (Five Times Amended) A system for electrically coupling a semiconductive device to an electrical apparatus, the system comprising:

an interposer, the interposer comprising:

a substrate comprised of an electrically insulating, ceramic material, the substrate having an outermost surface being configured for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said substrate; and

an electrical conductor on the substrate, the electrical conductor having a receiving end for connecting to the semiconductive device at electrically conductive terminals of said semiconductive device, and a terminal end for connecting to the electrical apparatus, wherein at least some of the terminals are located in the region between said semiconductive device and said outermost surface of said substrate; and

a connector in contact engagement with the semiconductive device and with said substrate for holding the semiconductive device stationary relative to the interposer by holding said semiconductive device against said interposer, wherein said contact engagement is effectuated through direct contact between the connector with the semiconductor device [directly] or through an adhesive in contact with said connector.

35. (Four Times Amended) A system for electrically coupling a semiconductive device to an electrical apparatus, the system comprising:

an interposer, the interposer comprising:

a substantially homogeneous, substantially planar sheet having an outermost surface and comprised of an electrically insulating, inorganic ceramic material, said sheet being configured for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said substrate; and

an electrical conductor on the sheet, the electrical conductor having a receiving end for connecting to a semiconductive device at electrically conductive terminals of said semiconductive device and a terminal end for connecting to an electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving

end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus, wherein at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said substrate; and

a connector for holding the semiconductive device stationary relative to the interposer, wherein said connector is in contact engagement with said semiconductive device, and with said sheet, wherein said contact engagement is effectuated through direct contact between the connector with the semiconductor device [directly] or through an adhesive in contact with said connector.

42. (Four Times Amended) A system for electrically coupling a semiconductive device to an electrical apparatus, the system comprising:

an interposer, the interposer comprising:

a substantially homogeneous, substantially planar sheet having an outermost surface and composed of an electrically insulating material selected from the group consisting of glass ceramics, devitrified ceramics, vitro ceramics, alumina, single oxide ceramics, and mixed oxide ceramics, and mixtures and derivatives thereof, said sheet being configured for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said substrate; and

an electrical conductor on the sheet, the electrical conductor having a receiving end for connecting to the semiconductive device at electrically conductive terminals of said semiconductive device and a terminal end for connecting to the electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus, wherein at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said substrate; and

a connector for holding the semiconductive device stationary relative to the interposer, wherein said connector is in contact engagement with said semiconductive device and with said sheet, wherein said contact engagement is effectuated through direct contact between the connector with the semiconductor device [directly] or through an adhesive in contact with said connector.

47. (Four Times Amended) A system for electrically coupling a semiconductive device to an electrical apparatus, the system comprising:

an interposer, the interposer comprising:

a substantially homogeneous, substantially planar sheet having an outermost surface and composed of an electrically insulating material selected from the group consisting of alumina, alumina with silica, alumina with silicates, alumina with derivatives of silicates, and mixtures and derivatives thereof, said sheet being configured for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said substrate; and

an electrical conductor on the sheet, the electrical conductor having a receiving end for connecting to the semiconductive device at electrically conductive terminals of said semiconductive device and a terminal end for connecting to the electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus, wherein at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said substrate; and

a connector for holding the semiconductive device stationary relative to the interposer, wherein said connector is in contact engagement with said semiconductive device and with said sheet, wherein said contact engagement is effectuated through direct contact between the connector with the semiconductor device [directly] or through an adhesive in contact with said connector [sheet].

52. (Four Times Amended) A system for electrically coupling a semiconductive device to an electrical apparatus, the system comprising:

an interposer, the interposer comprising:

a substantially homogeneous, substantially planar sheet having an outermost surface and composed of an electrically insulating material selected from the group consisting of boron nitrides, aluminum nitrides, and mixtures and derivatives thereof, said sheet being configured for receiving thereon a semiconductor device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said substrate; and

an electrical conductor on the sheet, the electrical conductor having a receiving end for connecting to a semiconductive device at electrically conductive terminals of said semiconductive device and a terminal end for connecting to an electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus, wherein at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said substrate; and

a connector for holding the semiconductive device stationary relative to the interposer, wherein said connector is in contact engagement with said semiconductive device and with said sheet, wherein said contact engagement is effectuated through direct contact between the connector with the semiconductor device [directly] or through an adhesive in contact with said connector [sheet].

57. (Four Times Amended) A system for electrically coupling a semiconductive device to an electrical apparatus, the system comprising:

an interposer, the interposer comprising:

a substantially homogeneous, substantially planar sheet having an outermost surface and composed of an electrically insulating material selected from the group consisting of oxides of silicon, silicate glass, and nucleated, substantially crystalline

glass, and mixtures and derivatives thereof, said sheet being configured for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said substrate; and

an electrical conductor on the sheet, the electrical conductor having a receiving end for connecting to the semiconductive device at electrically conductive terminals of said semiconductive device and a terminal end for connecting to the electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus, wherein at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said substrate; and

a connector for holding the semiconductive device stationary relative to the interposer, wherein said connector is in contact engagement with said semiconductive device and with said sheet, wherein said contact engagement is effectuated through direct contact between the connector with the semiconductor device [directly] or through an adhesive in contact with said connector.